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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/840,051	05/06/2004	Michael Bothe	041165-9060-00	6641
23409 7590 08/28/2007 MICHAEL BEST & FRIEDRICH LLP 100 E WISCONSIN AVENUE Suite 3300 MILWAUKEE, WI 53202			EXAMINER GETACHEW, ABIY	
			ART UNIT 2841	PAPER NUMBER
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary

Application No.

10/840,051

Applicant(s)

BOTHE ET AL.

Examiner

Abiy Getachew

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 09 May 2007.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-25 is/are pending in the application.
- 4a) Of the above claim(s) 16 is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-15 and 17-25 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 06 May 2004 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
 - ☐ Certified copies of the priority documents have been received in Application No. _____.
 - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: _____

DETAILED ACTION

1. This office action is a response to the restriction requirement filed on 05/09/2007.

Response to the Restriction Requirement

2. Applicant's election with traverse of in response, Applicant elects Species I for prosecution. Claims 1-15 and 17-25 read on Species I is acknowledged. The traversal is on the ground that there will be no serious burden if the restriction is withdrawn. This is not found persuasive because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement mailed on 05/09/2007, the election has been treated as an election without traverse (MPEP § 818.03(a)).

The requirement is still deemed proper and is therefore made FINAL.

Claim 16 is withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected invention.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

3. Claims 1,2,3,4,15,18,21,22,23,24 and 25 are rejected under 35 U.S.C. 102(b) as being by Sato et al. (4,712,160)

Regarding claim 1 Sato et al discloses a power supply circuit (Figure

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1B) comprising at least one transformer (3) which is connected to a primary side circuit (1) and to a secondary side circuit (2), wherein the primary side circuit (1) and the secondary side circuit (2) are each mounted on at least one separate circuit carrier (4), said circuit carriers (4) being mechanically and electrically coupled with one another and arranged in at least two different planes.[Column 3 paragraph 3 lines 37-45]

Regarding claim 2 as applied claim 1 above Sato et al. discloses wherein the plane defined by the at least one secondary side (2) circuit carrier (4) extends in a direction substantially transverse to the plane defined by the at least one primary side (1) circuit carrier (4). (See figure 1B)

Regarding claim 3 as applied claim 1 above Sato et al. discloses, wherein the primary side circuit (1) is mounted on a plurality of primary side circuit carriers (See figure 1B) the planes of which are substantially in parallel with one another (See figure 1B).

Regarding claim 4 as applied claim 1 above Sato et al. discloses, wherein the at least one primary side circuit carrier (4) is separated by an electrically insulating layer from the at least one secondary side circuit carrier (4). (See figure 1B element (9) i.e. the thermal conduction between the two circuit boards is also reduced by the clearances (9))

In regards to claim 15 as applied claim 1 above Sato et al. discloses, wherein the transformer (3) is an electromagnetic transformer (3) (See figure 1B) [Electromagnetism is the physics of the electromagnetic field: a field, encompassing all of space, composed of the electric field and the magnetic field.

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The electric field can be produced by stationary electric charges, and gives rise to the electric force, which causes static electricity and drives the flow of electric current in electrical conductors]

In regards to claim 18 as applied claim 1 above Sato et al. discloses, wherein at least one of the circuit carriers (4) is designed such that it discharges dissipated heat (See figure 2) produced during operation to the outside.

In regards to claim 21 as applied claim 1 above Sato et al. discloses wherein it is surrounded at least in part by an electrically insulating coating. [See the abstract, i.e. an integral module by a resin of high thermal conduction and electrical insulation properties, the device-mounted sides of the primary and secondary circuit boards facing each other]

In regards to claim 22, as applied claim 21 above Sato et al. discloses, wherein the electrically insulating coating is formed by a casting material.

[Column 6 paragraph 7 lines 36-43]

In regards to claim 23 and 24, as applied claim 15 above Sato et al. discloses, wherein electrical components (5 and 6) are integrated into a coil body of the transformer. (Referring to FIGS. 1(A) and 1(B): (1) is a primary circuit board on which the components of group A of FIG. 2 are integrated on one side; (2) is a secondary circuit board on which the components of group B of FIG. 2 are integrated on one side; (3) is a converter transformer; (4) is an electrical insulation material for joining the entire module)

In regards to claim 25, Sato et al. discloses, A method for producing a power supply circuit (See figure 1B) comprising at least one transformer (3), a primary

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side circuit (1) and a secondary side circuit (2), said method comprising the following steps: mounting the primary side circuit (1) on at least one primary side circuit carrier mounting (4) the secondary side circuit (2) on at least one separate secondary side circuit carrier (7) electrically and mechanically coupling the circuit carriers with the transformer, the circuit carriers being arranged in at least two different planes (See the Abstract).

Claim 5-14, 17, 19 and 20 are rejected under 103 (a) Sato et al. (4,712,160) in view of Bujatti et al. (4,925,723).

Regarding claim 5 as applied claim 1 above Sato et al. discloses, wherein at least one of the circuit carriers (4) circuit carriers comprises integrated resistors which can preferably be produced by thick film technology.

Bujatti et al. does not expressly disclose integrated resistors, which can preferably be produced by thick film technology.

Sato et al. discloses integrated resistors (14), which can preferably be produced by thick film technology [Column 1 paragraph 3 lines 42-48].

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. to obtain direct connections between specific points of the circuit on the upper surface and the metallization on the lower surface. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain integrated circuits formed on a substrate or circuit carrier.

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In regards to claim 6, as applied claim 1 above Sato et al. discloses. Wherein at least one of the circuit carriers (4) circuit carriers comprises integrated capacitors of a medium dielectric strength.

Bujatti et al. discloses integrated capacitors (14) of a medium dielectric strength [Column 3 paragraph 3 lines 13-21] [Examiner's interpretation of medium dielectric strength is as the value of a material as an electrical insulator or the resistance to the flow of electric current.

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain direct connections between specific points of the circuit on the upper surface and the metallization on the lower surface. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain integrated circuits formed on a substrate or circuit carrier.

In regards to claim 7, as applied claim 1 above Sato et al. discloses, wherein the integrated capacitors can be produced as a monolayer structure. (See figure 1B)

Sato et al. does not expressly disclose integrated capacitors.

Bujatti discloses wherein the integrated capacitors (14).

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Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain direct connections between specific points of the circuit on the upper surface and the metallization on the lower surface. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain integrated circuits formed on a substrate or circuit carrier.

In regards to claims 8 and 12 as applied claim 6 above Sato et al. discloses, wherein circuit carriers (4) circuit carriers comprises integrated capacitors of a medium dielectric strength.

Sato et al. does not disclose the integrated capacitors can be produced as a multilayer structure.

Bujatti et al. disclose the integrated capacitors can be produced as a multilayer structure. [Column 2 paragraph 4 lines 15-20]

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. to obtain direct connections between layers. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. to obtain integrated circuits formed on a substrate or circuit carrier.

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In regards to claims 9 and 13 as applied claim 6 above Sato et al. discloses, wherein circuit carriers (4)

Sato et al. does not disclose wherein the integrated capacitors can be produced by introducing a dielectric precursor into recesses.

Bujatti et al. disclose wherein the integrated capacitors (14) can be produced by introducing a dielectric precursor (See figure 2C element 23) into recesses (16).

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain integrated circuits formed on a substrate or circuit carrier.

In regards to claim 10 and 14 as applied claim 1 above Sato et al. discloses, wherein at least one of the circuit carriers (4)

Sato et al. does not expressly disclose integrated capacitors of a high dielectric strength.

Bujatti et al. discloses integrated capacitors (14) of a high dielectric strength [Column 3 paragraph 3 lines 13-21] [Examiner's interpretation of medium dielectric strength is as the value of a material as an electrical insulator or the resistance to the flow of electric current.

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

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At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain direct connections between specific points of the circuit on the upper surface and the metallization on the lower surface. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain integrated circuits formed on a substrate or circuit carrier.

In regards to claim 11 as applied claim 10 above Sato et al. discloses, a monolayer structure (See figure 1B).

Sato et al. does not expressly discloses the integrated capacitors.

Bujatti et al. discloses integrated capacitors (14).

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. to obtain integrated capacitors can be produced as monolayer structure. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. to obtain integrated circuits formed on a substrate or circuit carrier as monolayer structure.

In regards to claim 17 as applied claim 1 above Sato et al. discloses, wherein at least one of the circuit carriers (4)

Sato et al. does not expressly discloses circuit carriers produced from a ceramic material.

Bujatti et al. discloses substrate produced from a ceramic material. [Column

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1 paragraph 2 lines 15-25]

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. to manufacturing of integrated circuits formed on a substrate or circuit carrier. So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. to obtain circuit carriers produced from a ceramic material.

In regards to claim 19, as applied claim 1 above Sato et al. discloses, wherein the individual circuit carriers (4)

Sato et al. does not expressly discloses mechanically connectable to one another by means of joint sintering, adhesive bonding or soldering.

Bujatti et al. discloses mechanically connectable to one another by means of joint sintering, adhesive bonding or soldering. [Column 3 paragraph 2 lines 5-12]

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain connections between specific points of the circuit on the upper surface and the metallization on the lower surface by means of joint adhesive. So therefore, it would have been obvious to combine Sato et al.

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and Bujatti et al. in order to mechanically connectable to one another by means of joint sintering, adhesive bonding or soldering.

In regards to claim 20, as applied claim 1 above Sato et al. discloses, wherein the individual circuit carriers are electrically connectable to one another through vias in at least one insulation layer.

Sato et al. does not expressly discloses mechanically connectable to one another by means of joint sintering, adhesive bonding or soldering.

Bujatti et al. discloses mechanically connectable to one another by means of joint sintering, adhesive bonding or soldering. [Column 1 paragraph 2 lines 15-35]

Sato et al. and Bujatti et al. are analogous art and both arts in the same area of invention, manufacturing of integrated circuits formed on a substrate or circuit carrier.

At the time of the invention it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain connections between specific points of the circuit on the upper surface and the metallization on the lower surface by means of cutting holes, referred in the teaching as "Via holes" So therefore, it would have been obvious to combine Sato et al. and Bujatti et al. in order to obtain mechanically connectable to one another by means of joint sintering, adhesive bonding or soldering.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Abiy Getachew whose telephone number is

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(571) 272 6932. The examiner can normally be reached on Monday to Friday 8Am to 4:30Pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Dean A. Reichard can be reached on (571) 272 1984. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Abiy Getachew
Examiner
Art Unit 2841

A.G.
August 6, 2007


TUAN T. DINH
PRIMARY EXAMINER